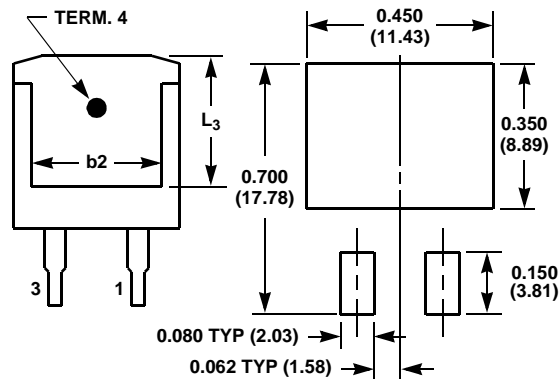
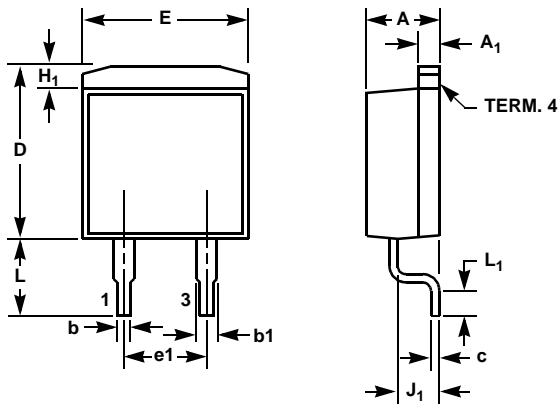


**TO-263**  
**SURFACE MOUNT JEDEC STYLE TO-263 PLASTIC PACKAGE**  
**(FOR RECTIFIERS ONLY)**



**MINIMUM PAD SIZE RECOMMENDED FOR SURFACE-MOUNTED APPLICATIONS**

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.170	0.180	4.32	4.57	-
A <sub>1</sub>	0.048	0.052	1.22	1.32	3, 4
b	0.030	0.034	0.77	0.86	3, 4
b <sub>1</sub>	0.045	0.055	1.15	1.39	3, 4
b <sub>2</sub>	0.310	-	7.88	-	2
c	0.018	0.022	0.46	0.55	3, 4
D	0.405	0.425	10.29	10.79	-
E	0.395	0.405	10.04	10.28	-
e <sub>1</sub>	0.200 BSC		5.08 BSC		6
H <sub>1</sub>	0.045	0.055	1.15	1.39	-
J <sub>1</sub>	0.095	0.105	2.42	2.66	-
L	0.175	0.195	4.45	4.95	-
L <sub>1</sub>	0.090	0.110	2.29	2.79	3, 5
L <sub>3</sub>	0.315	-	8.01	-	2

**NOTES:**

1. No current JEDEC outline for this package.
2. L<sub>3</sub> and b<sub>2</sub> dimensions established a minimum mounting surface for terminal 4.
3. Dimension (without solder).
4. Add typically 0.002 inches (0.05mm) for solder plating.
5. L<sub>1</sub> is the terminal length for soldering.
6. Position of lead to be measured 0.120 inches (3.05mm) from bottom of dimension D.
7. Controlling dimension: Inch.
8. Revision 7 dated 5-99.